



## Technical Data Sheet

### AP-80-S Series

## Thermal/EMI Absorber Silicone Compounds

#### A. Description

**FeedBond® AP-80-S Series** one-component, thermally curable, silicone compound is developed for IC packaging application, has high thermal conductivity, good thermal stability, and can also suppress or absorb noise radiation from electronic equipment. The AP-80-S series is also compatible with excellent thermal conductivity and absorbing performance.

#### B. Properties

- No added solvents.
- Applicable to dispensing operations.
- High thermal conductivity to meet industry trend of increasing IC power Good.
- EMI suppression over a wide frequency range.

#### C. Advantages

- Performance advantage comes from dual functional properties of thermal conductivity and EMI reduction.
- EMI is reduced, signal integrity is better, and the reliability of electronic products is improved.
- Temperature stability and low volatility of the product, stable performance of electronic products.
- Compliance with RoHS and REACH regulations.



## D. Specifications

### UNCURED PROPERTIES

Product Name	Appearance	Work Life hrs	Viscosity @25°C cps	Thixotropic Index
Method	Visual	FT-P024	FT-P006	FT-P008
AP-80-S01	Gray	10	5,000	4.4
AP-80-S02			6,500	4.3
AP-80-S03			7,000	4.2
AP-80-S04			11,000	2.8
AP-80-S05			18,000	2.6
AP-80-S06			20,000	2.5
AP-80-S07			24,000	2.4

### CURED PROPERTIES

Product Name	Appearance	Specific Gravity	Hardness Type 00	Thermal Conductivity W/mK	Resistance $\Omega$	Temp. Range °C
Method	Visual	FT-P001	FT-P037	Hot Disk <sup>1</sup>	Resistance meter	NA
AP-80-S01	Gray	2.3	20	5.0	$> 10^{11}$	-40 ~ 125
AP-80-S02			22	9.0	$> 10^{11}$	-40 ~ 125
AP-80-S03			25	12.0	$> 10^{11}$	-40 ~ 125
AP-80-S04			40	13.0	$> 10^5$	-40 ~ 125
AP-80-S05			43	14.0	$< 10^3$	-40 ~ 125
AP-80-S06			49	14.5	$< 10^3$	-40 ~ 125
AP-80-S07			54	15.0	$< 10^3$	-40 ~ 125

1. Hot Disk : Sensor 5501 、Slab model ◦

### CURE CONDITION

### TEST DESCRIPTION

Standard Cure Condition

Oven 125°C/ 90min  
or  
Oven 150°C / 60min

### PACKAGING & STORAGE

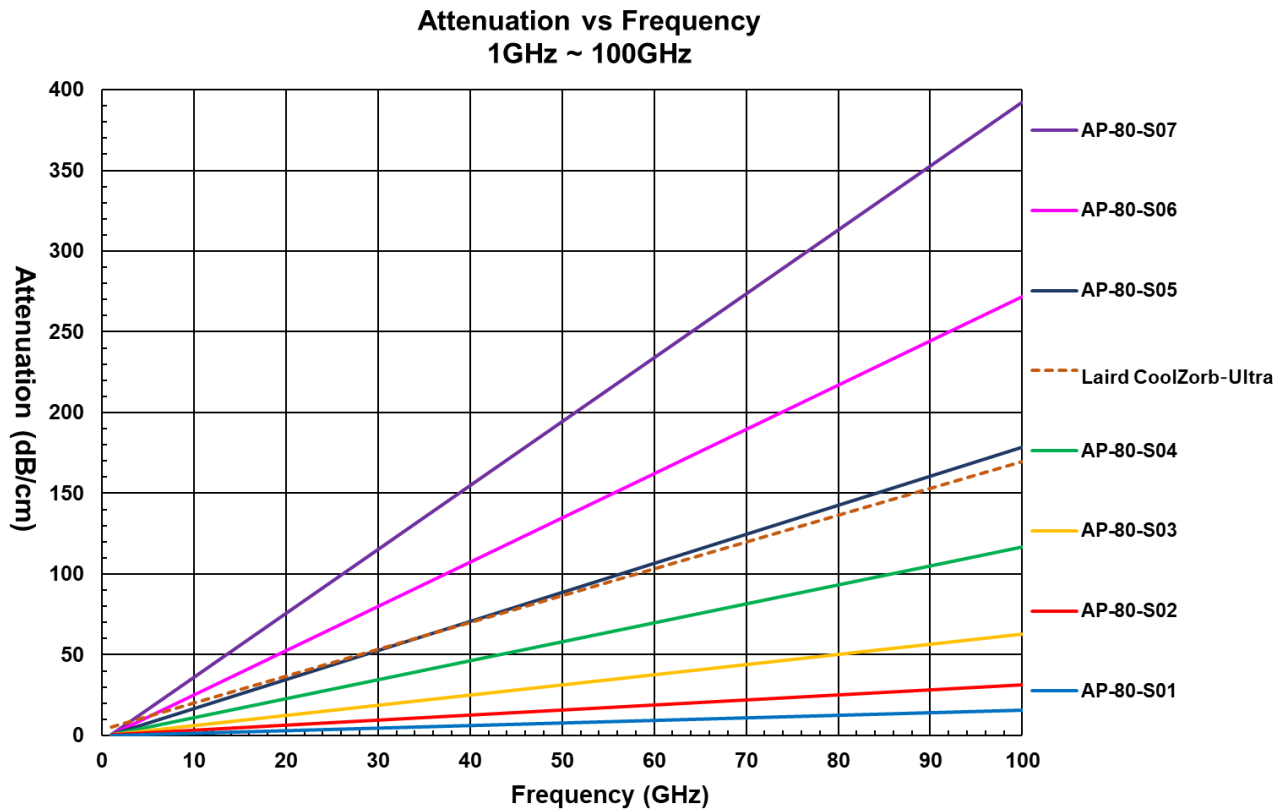
Packaging 50gm (Syringe Barrel)

Storage Condition -40°C 、3 months

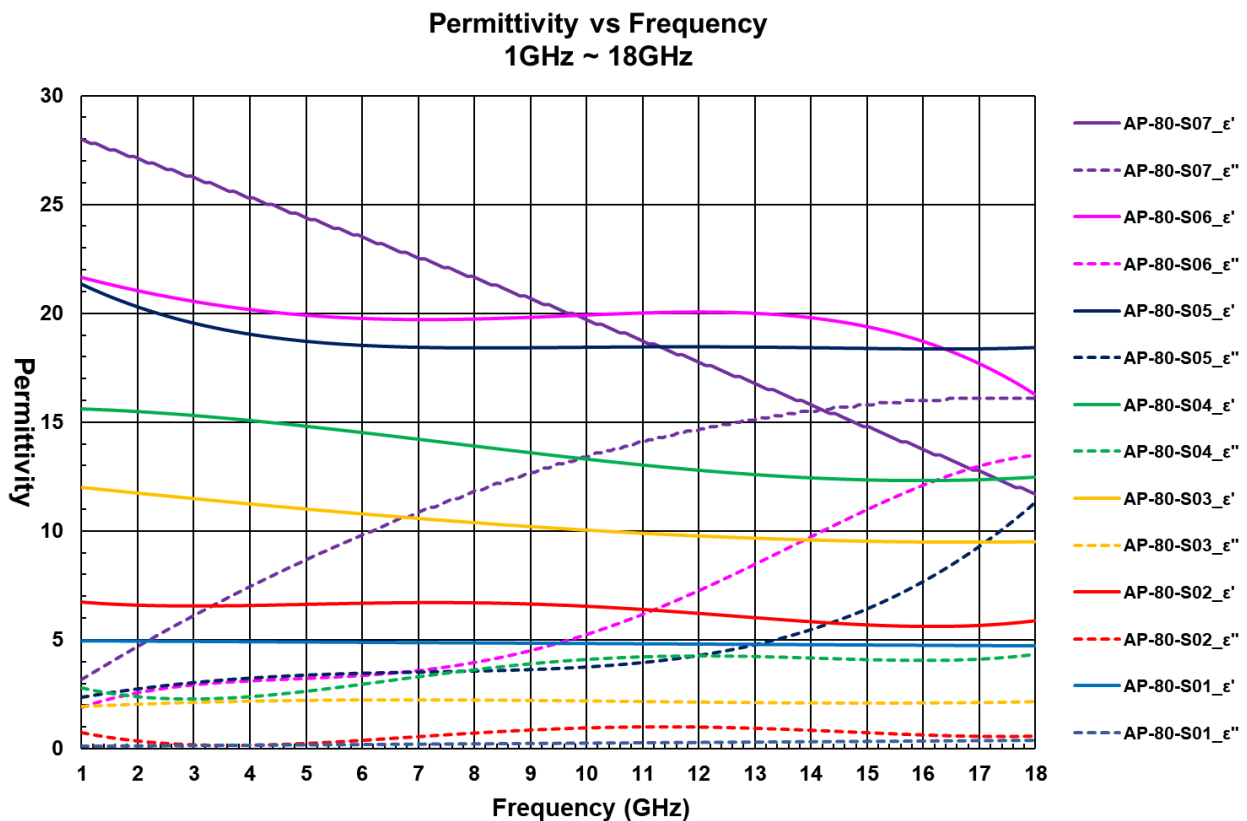
The tables shown above are typical values only. If you need to write a specification, please request our current Standard Release Specification.



## E. Attenuation 1GHz ~ 100GHz :



## F. Permittivity 1GHz ~ 18GHz:





## G. Instruction:

All surfaces must be clean and free of contaminants that will inhibit the cure of AP-80-S Series. Examples of inhibiting contaminants are sulfur containing materials, plasticizers, urethanes, amine containing materials and organometallic compounds – especially organotin compounds.  
If a substrate's ability to inhibit cure is unknown, a small-scale test should be run to determine compatibility.

## H. Thawing

Place the container to stand vertically for 60mins. **DO NOT** open the container before adhesive reaches ambient temperature to prevent the moisture condensation. Any moisture that collects on the thawed container should be removed prior to use. Adhesives that appear to have separated should not be used.

## I. Storage

Thermally Conductive Silicone Compounds should be stored @ -40°C. The shelf life of the material is only valid when the material has been stored at the correct storage condition.

## J. Availability

FeedBond® adhesives are packaged in syringes or pots per customer specification. For the details, please contact our Customer Service or sales department.

## K. Note

This information corresponds to our current knowledge on the subject. It is offered solely to provide possible suggestions for your own experimentation. It is not intended, however, to substitute for any testing you may need to conduct and to determine the suitability of our products by yourself for your particular purposes. This information may be subject to revision as new knowledge and experience become available. Since we cannot anticipate all variations in actual end-use conditions, Feedpool makes no warranties and assumes no liability in connection with any use of this information. Nothing in this publication is to be considered as a license to operate under or a recommendation to infringe any patent right.

Feedpool Technology Co.,Ltd.

Address: No.7,Lane 607,Yung Ping Road, Yangmei City Taoyuan, Taiwan.

Website: [www.feedpool.com](http://www.feedpool.com) Tel: 886-3-4813158 Fax: 886-3-4813059